Subject: *SOLVED* NIC Bonding/Grouping

Posted by joelee on Thu, 12 Jul 2007 19:10:20 GMT

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I've come across this how-to article regarding the concept of NIC Bonding or Grouping and wanted to know if OVZ supports that kind of setup. Here's a link to the article:

http://howtoforge.com/nic_bonding#comment-3628

Here's an excert from the article:

"The concept of NIC Bonding (or sometimes called NIC Teaming) is that you have two NICs bonded together to appear as if they are the same physical device. I.e. They will both present the same Hardware (MAC) address. This is accomplished through the ifenslave utility, which enables the kernel to see/use only one device, while it sends out packtes via the two slave devices using a round-robbin scheduler."

Joe

Subject: Re: NIC Bonding/Grouping

Posted by Vasily Tarasov on Fri, 13 Jul 2007 08:04:39 GMT

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You can use bonding on HN with OpenVZ, but it isn't possible to use bond device inside VE.

HTH,
Vasily

Subject: Re: NIC Bonding/Grouping

Posted by joelee on Fri, 13 Jul 2007 13:25:42 GMT

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Great! Thanks vasily...

Subject: Re: NIC Bonding/Grouping

Posted by rudal on Fri, 28 Mar 2008 07:57:31 GMT

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Is this still the case that we cant use the bond interface inside the VE?

Thanks.